

Heterogeneous Integration & Assembly Materials

Material Type	Material Name	Flux Type	Comments
Flip-Chip and Ball-Attach	NC-809	NC	<i>Application:</i> Dipping, Printing, and Pin Transfer Enhanced wetting, compatible with wide variety of CUF/MUF. Suitable for no-clean process, good wetting onto gold surface.
	WS-446HF	WS	<i>Application:</i> Dipping and Pin Transfer Best all-around halogen-free flip-chip flux, easily cleaned. Suitable for one-step Cu OSP process for sphere size 0.25mm and above
Flip-Chip Flux	WS-446	WS	Best flux for poor solderability, halogen-containing
	WS-446HF	WS	Best all-around halogen-free flip-chip flux, easily cleaned
	NC-26-A	ULR, NC	Best compatibility with CUF/MUF
	NC-26S	ULR, NC	Avoids capillary flow up to die surface for fine-pitch devices
Ball-Attach Flux	WS-446-AL	WS	Best flux for poor solderability, halogen-containing
	WS-829	WS	For sphere size <0.25mm and fine-pitch high-density ball attach, best cleanability
	WS-823	WS	Best all-around halogen-free ball-attach flux, easily cleaned
	WS-676	WS	For printing on wafer, suitable for WLCSP
	WS-759	WS	For printing on wafer and panel, suitable for FOW/PLP
SiP Solder Paste	SiPaste® 3.2HF	WS	Type 6, Type 7, and Type 8 solder paste suitable for ultrafine-pitch printing
	SiPaste® C201HF	C*	
	SiPaste® SMQ77	NC	
Formic Acid Adhesive Solution	NC-702	NC	Holding die or chip in place before reflow, for formic acid reflow, near-zero residue

*C: Cleanable, easily cleanable residue with semi-aqueous solution OR solvent

Contact our engineers: askus@indium.com
Learn more: www.indium.com

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.



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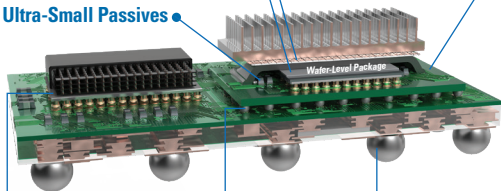
Thermal Management

- TIM2 / Heat-Spring®
- TIM1
 - Flux-coated preforms
 - Solder TIM
 - Liquid Metal Paste
 - Liquid Metal

System-in-Package

- Wafer-Level Ball-Attach Flux
 - Water-soluble
 - Halogen-free
- Ultrafine-Pitch Solder Paste
 - Water-soluble, ultra-low residue, and standard no-clean
 - Halogen-free
 - Type 6, Type 7, and Type 8

Ultra-Small Passives



Memory and Flip-Chip / 3D Logic

- Wafer Bumping (Bump Fusion) Flux
 - Water-soluble
 - Spin-on and jetting
 - Halogen-free
- Flip-Chip Flux
 - Water-soluble, ultra-low residue, and standard no-clean
 - Dipping, spraying, and jetting
 - Halogen-free and halogenated

Ball Grid Array

- Ball-Attach Flux
 - Water-soluble
 - Pin transfer and printing
 - Halogenated and halogen-free

SMT

- Solder Paste
- Solder Wire
- Solder Flux
- Preforms
- Bar Solder

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